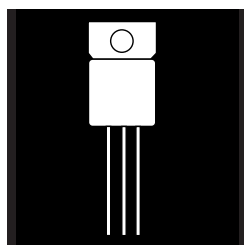


# RADIATION HARDENED POWER MOSFETS IN HERMETIC ISOLATED PACKAGE P-CHANNEL



## 100V, 10 Amp, P-Channel, Radiation Hardened Power MOSFET In A Hermetic Metal Package

### FEATURES

- Rated As Radiation Hard
- Avalanche Energy Rated
- Isolated Hermetic Package
- Low  $R_{DS(on)}$
- High Switching Speeds
- Screened to TX, TXV And S Levels

### DESCRIPTION

This P-Channel Power MOSFET product is in a hermetic package and features the latest radiation hard power semiconductor. This semiconductor die is processed to achieve hardened characteristics. Total dose hardness is available at 100K and 1000K rads with neutron hardness at  $1E14$  N/CM<sup>2</sup>. Dose rate hardness, without current limiting, is to rates of  $1E9$  rads/sec, and with current limiting  $2E12$  rads/sec. The heavy ion survival rate, from a single event drain burn out, is a linear energy transfer (LET) of 35 at 80 Volts.

### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$

|                                                                |                                               |
|----------------------------------------------------------------|-----------------------------------------------|
| Drain Source Voltage, $V_{DS}$ .....                           | - 100 V                                       |
| Drain Gate Voltage ( $R_{GS} = 20\text{KW}$ ), $V_{DGR}$ ..... | - 100 V                                       |
| Continuous Drain Current, $I_D$ .....                          | - 10.2 A                                      |
| Continuous Drain Current, $I_D$ @ $100^\circ\text{C}$ .....    | - 6.4 A                                       |
| Pulsed Drain Current, $I_{DM}$ .....                           | - 41 A                                        |
| Max. Power Dissipation, $P_D$ .....                            | 70 W                                          |
| Max. Power Dissipation, $P_D$ @ $100^\circ\text{C}$ .....      | 32 W                                          |
| Linear Derating Factor .....                                   | .51 W/ $^\circ\text{C}$                       |
| Operating Temperature, $T_J$ .....                             | -55 $^\circ\text{C}$ TO +150 $^\circ\text{C}$ |
| Storage Temperature, $T_{stg}$ .....                           | -55 $^\circ\text{C}$ TO +175 $^\circ\text{C}$ |
| Lead Temperature - 1/16" from case for 10 sec .....            | 300 $^\circ\text{C}$                          |

### RAD HARDNESS RATING $T_C = 25^\circ\text{C}$

| CHARACTERISTIC | INITIAL    | POST RADIATION - RADS |            |            |
|----------------|------------|-----------------------|------------|------------|
|                |            | 10K                   | 100K       | 1MEG       |
| $BV_{DSS}$     | 100V       | 100V                  | 100V       | 95V        |
| $R_{DS(on)}$   | .60W       | .60W                  | .60W       | .86W       |
| $V_{GS}$       | 2.0 - 4.0V | 2.0 - 4.0V            | 2.0 - 4.0V | 2.0 - 4.0V |

3.1

OM9130STC

ELECTRICAL CHARACTERISTICS: (T<sub>C</sub> = 25°C unless otherwise noted)  
STATIC P/N OM9130STC (100V, P-Channel)

| Parameter                                                                | Min. | Typ. | Max.  | Units | Test Conditions                                                               |
|--------------------------------------------------------------------------|------|------|-------|-------|-------------------------------------------------------------------------------|
| BV <sub>DSS</sub> Drain-Source Breakdown Voltage                         | 100  |      |       | V     | V <sub>GS</sub> = 0, I <sub>D</sub> = 250 mA                                  |
| V <sub>GS(th)</sub> Gate-Threshold Voltage                               | 2.0  |      | 4.0   | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 mA                   |
| I <sub>GSS</sub> Gate-Body Leakage                                       |      |      | ± 100 | nA    | V <sub>GS</sub> = ± 20 V                                                      |
| I <sub>DSS</sub> Zero Gate Voltage Drain Current                         |      | 0.1  | 0.25  | mA    | V <sub>DS</sub> = Max. Rat., V <sub>GS</sub> = 0                              |
|                                                                          |      | 0.2  | 1.0   | mA    | V <sub>DS</sub> = 0.8 Max. Rat., V <sub>GS</sub> = 0, T <sub>C</sub> = 125° C |
| I <sub>D(on)</sub> On-State Drain Current <sup>1</sup>                   | 10.2 |      |       | A     | V <sub>DS</sub> = 2 V <sub>DS(on)</sub> , V <sub>GS</sub> = 10 V              |
| R <sub>DS(on)</sub> Static Drain-Source On-State Resistance <sup>1</sup> |      |      | 0.34  |       | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A                                  |
| R <sub>DS(on)</sub> Static Drain-Source On-State Resistance <sup>1</sup> |      |      | 0.68  |       | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A,, T <sub>C</sub> = 125 C         |

DYNAMIC

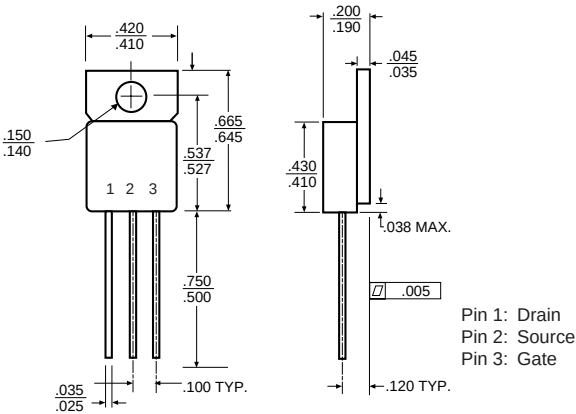
|                                                       |     |     |  |      |                                                                |
|-------------------------------------------------------|-----|-----|--|------|----------------------------------------------------------------|
| g <sub>fs</sub> Forward Transconductance <sup>1</sup> | 2.0 |     |  | S(M) | V <sub>DS</sub> = 2 V <sub>DS(on)</sub> , I <sub>D</sub> = 6 A |
| C <sub>iss</sub> Input Capacitance                    |     | 500 |  | pF   | V <sub>GS</sub> = 0                                            |
| C <sub>oss</sub> Output Capacitance                   |     | 460 |  | pF   | V <sub>DS</sub> = 25 V                                         |
| C <sub>rss</sub> Reverse Transfer Capacitance         |     | 100 |  | pF   | f = 1 MHz                                                      |
| t <sub>d(on)</sub> Turn-On Delay Time                 |     | 50  |  | ns   | V <sub>DD</sub> = 50 V, I <sub>D</sub> @ 6 A                   |
| t <sub>r</sub> Rise Time                              |     | 115 |  | ns   | R <sub>θ</sub> = 50 W, V <sub>DS</sub> = 10 V                  |
| t <sub>d(off)</sub> Turn-Off Delay Time               |     | 115 |  | ns   |                                                                |
| t <sub>f</sub> Fall Time                              |     | 115 |  | ns   |                                                                |

BODY-DRAIN DIODE RATINGS AND CHARACTERISTICS

|                                                          |  |     |    |    |                                                                              |
|----------------------------------------------------------|--|-----|----|----|------------------------------------------------------------------------------|
| I <sub>S</sub> Continuous Source Current (Body Diode)    |  |     | 12 | A  | Modified MOSPOWER symbol showing the integral P-N Junction rectifier.        |
| I <sub>SM</sub> Source Current <sup>1</sup> (Body Diode) |  |     | 48 | A  |                                                                              |
| V <sub>SD</sub> Diode Forward Voltage <sup>1</sup>       |  | 1.7 |    | V  | T <sub>C</sub> = 25 C, I <sub>S</sub> = -12 A, V <sub>GS</sub> = 0           |
|                                                          |  |     |    |    | T <sub>C</sub> = 25 C, I <sub>S</sub> = -12 A, V <sub>GS</sub> = 0           |
| t <sub>rr</sub> Reverse Recovery Time                    |  | 400 |    | ns | T <sub>J</sub> = 25 C, I <sub>F</sub> = -12A, dI <sub>F</sub> /ds = 100 A/ms |

1 Pulse Test: Pulse Width 300msec, Duty Cycle 2%.

MECHANICAL OUTLINE



ORDERING INFORMATION

